CLEANING DEVICE FOR CHECKING WAFERS IN REAL TIME, AND USE METHOD AND INSPECTION METHOD THEREOF

Abstract

The present invention provides a cleaning device, comprising: a clamping unit; a plurality of spraying arms rotatably arranged above the clamping; a spray nozzle mounted at an end of each spraying arm; a remedy unit rotatably arranged above the clamping unit; a plurality of first inspection units, each arranged on each spraying arm and suitable to check each spray nozzle for its spraying state; a second inspection unit, arranged above the clamping unit and suitable to check a wafer body for its cleaning state on the clamping unit; and a terminal controller, electrically connecting to the clamping unit, a driving apparatus of both each spraying arm and the remedy unit, each first inspection unit and the second inspection unit, respectively, making it possible to control the remedy unit to release the remedy medium at occurrence of an anomaly by the terminal controller, so as to remedy the wafer body.

Fig 1